

Features

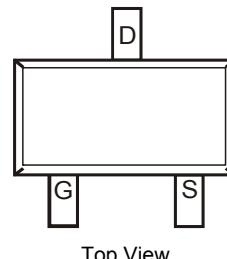
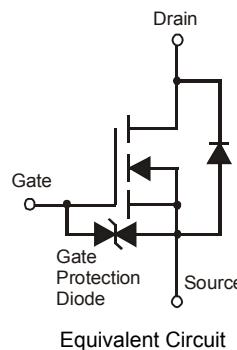
- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- **ESD Protected up to 2kV**
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**
- **Qualified to AEC-Q101 standards for High Reliability**

Mechanical Data

- Case: SOT523
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish — Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Weight: 0.002 grams (approximate)


SOT523


Top View



Top View

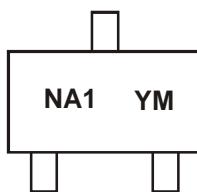
Ordering Information (Note 3)

Part Number	Qualification	Case	Packaging
DMG1012T-7	Commercial	SOT523	3000/Tape & Reel
DMG1012TQ-7	Automotive	SOT523	3000/Tape & Reel

Notes:

1. No purposefully added lead.
2. Diodes Inc.'s "Green" policy can be found on our website at <http://www.diodes.com>.
3. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information



NA1 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: W = 2009)
 M = Month (ex: 9 = September)

Date Code Key

Year	2009	2010	2011	2012	2013	2014	2015					
Code	W	X	Y	Z	A	B	C					
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V_{DSS}	20	V
Gate-Source Voltage			V_{GSS}	± 6	V
Continuous Drain Current (Note 4)	Steady State	$T_A = 25^\circ\text{C}$ $T_A = 85^\circ\text{C}$	I_D	0.63 0.45	A
Pulsed Drain Current			I_{DM}	6	A

Thermal Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 4)	P_D	0.28	W
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	452	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

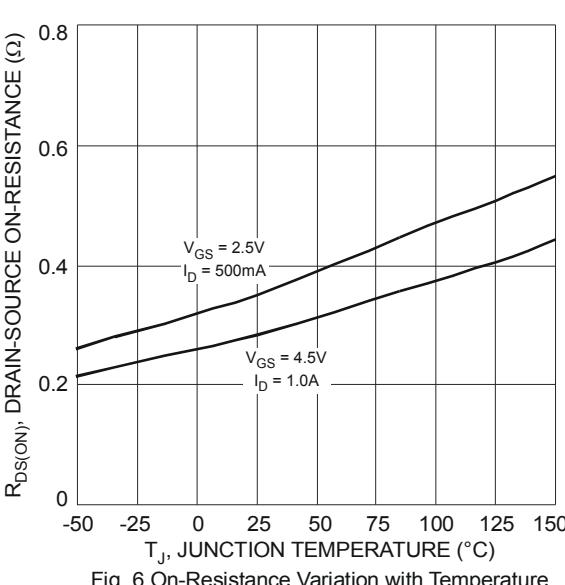
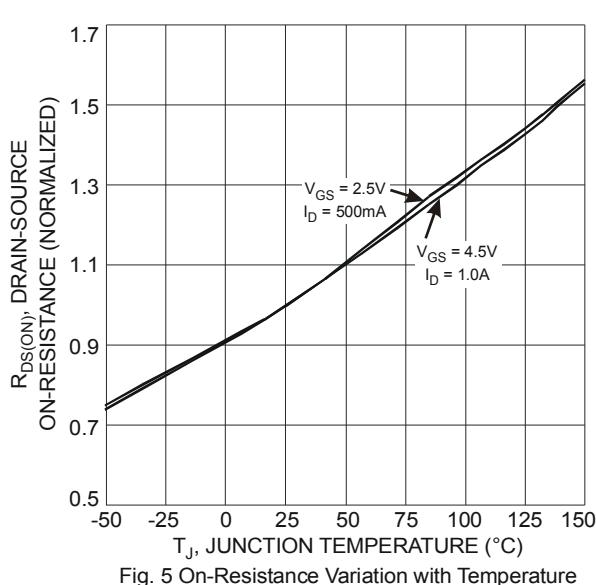
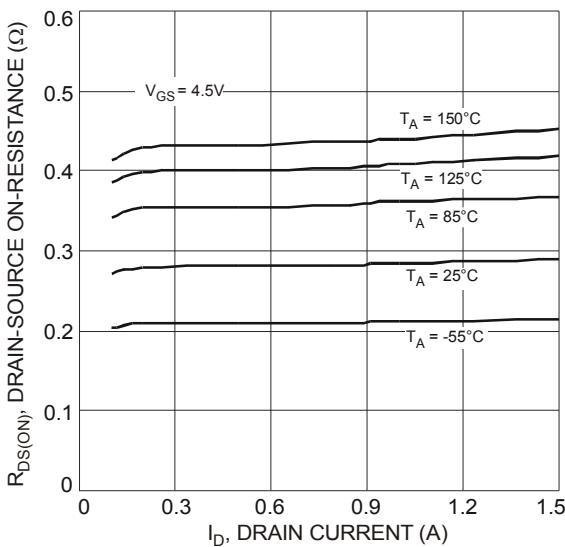
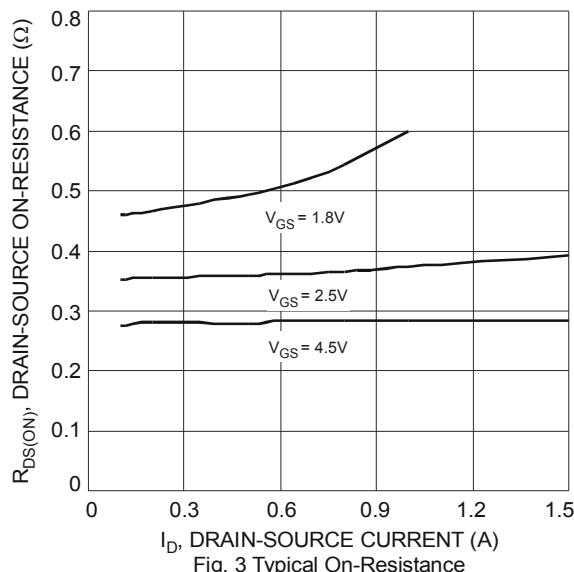
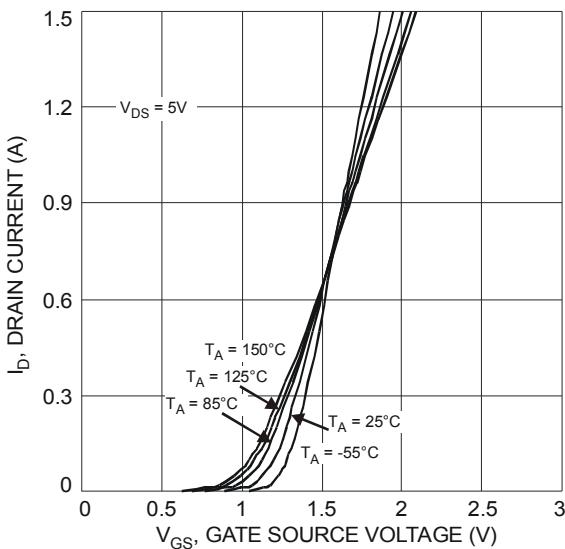
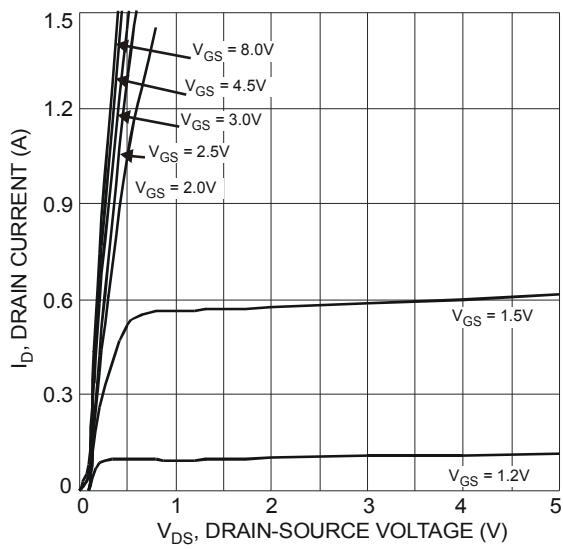
Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)						
Drain-Source Breakdown Voltage	BV_{DSS}	20	-	-	V	$V_{GS} = 0\text{V}$, $I_D = 250\mu\text{A}$
Zero Gate Voltage Drain Current $T_J = 25^\circ\text{C}$	I_{DSS}	-	-	100	nA	$V_{DS} = 20\text{V}$, $V_{GS} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	-	-	± 1.0	μA	$V_{GS} = \pm 4.5\text{V}$, $V_{DS} = 0\text{V}$
ON CHARACTERISTICS (Note 5)						
Gate Threshold Voltage	$V_{GS(th)}$	0.5	-	1.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(\text{ON})}$	-	0.3	0.4	Ω	$V_{GS} = 4.5\text{V}$, $I_D = 600\text{mA}$
			0.4	0.5		$V_{GS} = 2.5\text{V}$, $I_D = 500\text{mA}$
			0.5	0.7		$V_{GS} = 1.8\text{V}$, $I_D = 350\text{mA}$
Forward Transfer Admittance	$ Y_{fs} $	-	1.4	-	S	$V_{DS} = 10\text{V}$, $I_D = 400\text{mA}$
Diode Forward Voltage (Note 5)	V_{SD}		0.7	1.2	V	$V_{GS} = 0\text{V}$, $I_S = 150\text{mA}$
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{iss}	-	60.67	-	pF	$V_{DS} = 16\text{V}$, $V_{GS} = 0\text{V}$, $f = 1.0\text{MHz}$
Output Capacitance	C_{oss}	-	9.68	-	pF	
Reverse Transfer Capacitance	C_{rss}	-	5.37	-	pF	
Total Gate Charge	Q_g	-	736.6	-	pC	$V_{GS} = 4.5\text{V}$, $V_{DS} = 10\text{V}$, $I_D = 250\text{mA}$
Gate-Source Charge	Q_{gs}	-	93.6	-	pC	
Gate-Drain Charge	Q_{gd}	-	116.6	-	pC	
Turn-On Delay Time	$t_{D(on)}$	-	5.1	-	ns	$V_{DD} = 10\text{V}$, $V_{GS} = 4.5\text{V}$, $R_L = 47\Omega$, $R_G = 10\Omega$, $I_D = 200\text{mA}$
Turn-On Rise Time	t_r	-	7.4	-	ns	
Turn-Off Delay Time	$t_{D(off)}$	-	26.7	-	ns	
Turn-Off Fall Time	t_f	-	12.3	-	ns	

Notes:

4. Device mounted on FR-4 PCB.

5. Short duration pulse test used to minimize self-heating effect.



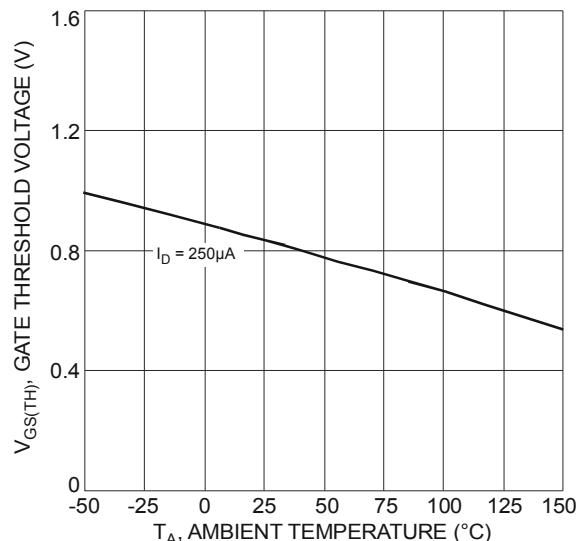


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

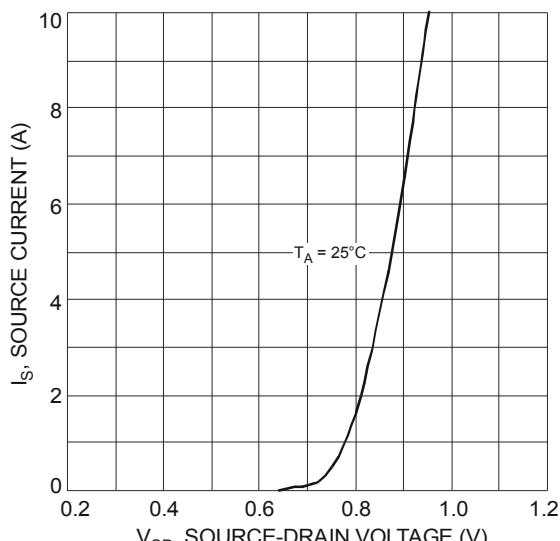


Fig. 8 Diode Forward Voltage vs. Current

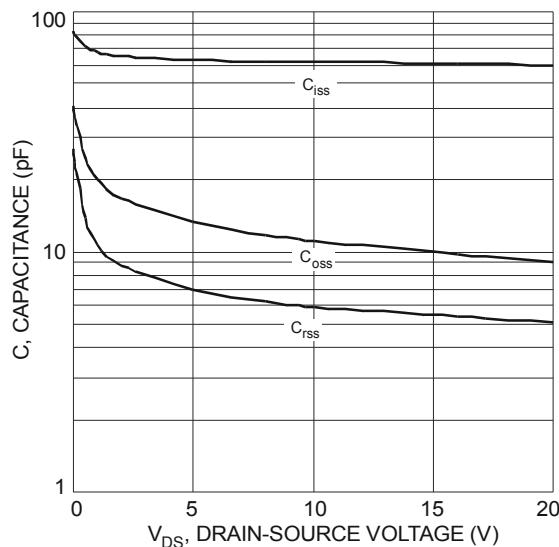


Fig. 9 Typical Capacitance

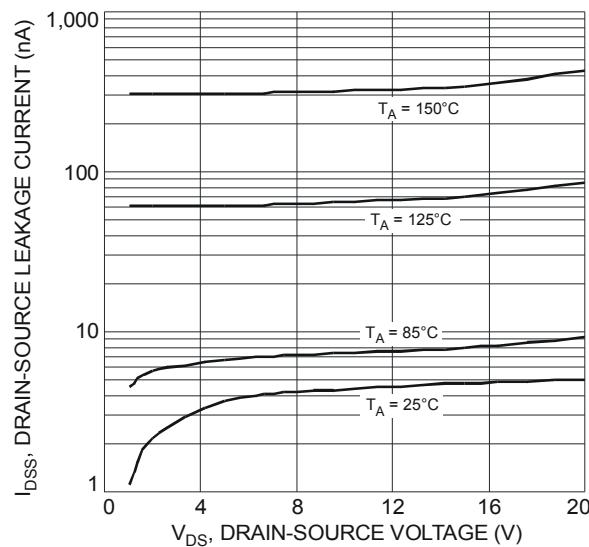


Fig. 10 Typical Drain-Source Leakage Current vs. Drain-Source Voltage

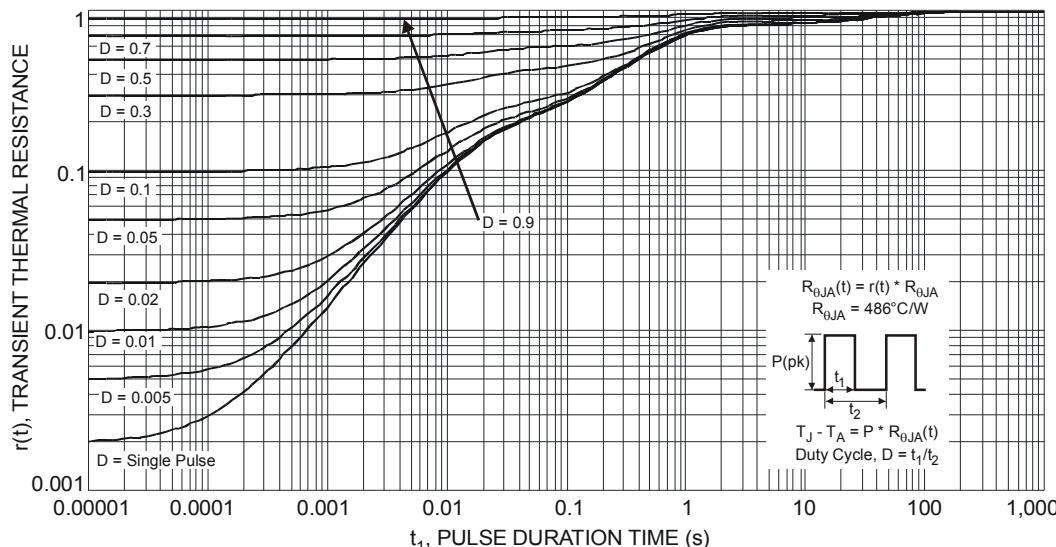
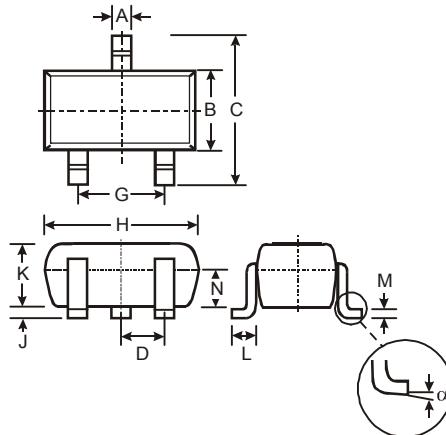


Fig. 11 Transient Thermal Response

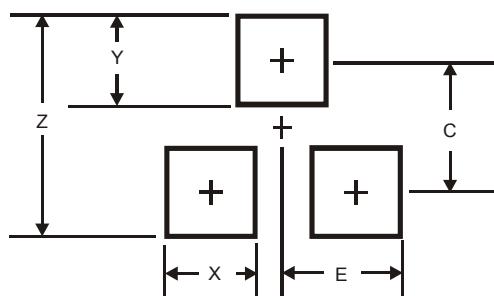
Package Outline Dimensions



SOT523			
Dim	Min	Max	Typ
A	0.15	0.30	0.22
B	0.75	0.85	0.80
C	1.45	1.75	1.60
D	—	—	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
J	0.00	0.10	0.05
K	0.60	0.80	0.75
L	0.10	0.30	0.22
M	0.10	0.20	0.12
N	0.45	0.65	0.50
α	0°	8°	—

All Dimensions in mm

Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.8
X	0.4
Y	0.51
C	1.3
E	0.7

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